11th European Wet Users Meeting

Thursday, April 4, 2019, 14:00 – 18:00

Donauhallen, Donaueschingen, Germany

Organized by VDE/VDI-GMM Gesellschaft für Mikroelektronik, Mikro- und Feinwerktechnik
(VDE/VDI-GMM Society for Microelectronics, Micro and Precision Engineering)
in cooperation with zwickerconsult and ErzM-Technologies

Agenda

13:00	Welcome coffee, tea, softdrinks
14:00	Opening Remarks Knut Gottfried Fraunhofer ENAS & ErzM-Technologies, Chemnitz, Germany
	Wet Processes: Session 1 Session Chair: Gerfried Zwicker, zwickerconsult, Itzehoe, Germany
14:15	L: Development and Qualification of Flow Dynamics for eless UBM Stefan Zürcher AP&S, Donaueschingen, Germany
14:40	L: Minimum Undercut for UBM Etch Michael Awdshiew Veeco GmbH, Aschheim, Germany
15:05	L: Filter Health Characterization and Risk-Mitigation Recommendations for Hot Phosphoric Applications Sebastian Dilly Pall Microelectronics, Dreieich, Germany
15:30	L: What is the Most Critical Challenge for Fittings to Fulfill 7 nm Node ? Hirofumi Katsute Flowell Corp., Yokohama, Kanagawa, Japan
15:55	**Coffee Break**
	Wet Processes: Session 2 Session Chair: Patrick Ong, IMEC Leuven, Belgium
16:30	S: Porous Silicon and Its Applications Shervin Keshavarzi and Alexander Filbert Fachhochschule Furtwangen, Germany
16:45	L: Dissolved NH_3 for Advanced Semiconductor Application Jens Fittkau, Christiane Le Tiec, and Ulrich Brammer MKS Instruments, Munich, Germany
17:10	L: Impacts on Particle Qualification of Wet Process SC Equipment Prior to Delivery Kangfa Deng AP&S, Donaueschingen, Germany

17:40	End of Wet Users Meeting / time for networking and discussion
18:00	Bus Tour to the “Hirsch”-Brewery
18:30	Brewery tour, followed by the joined workshop dinner
23:30	Return by bus to Donaueschingen

40th European CMP Users Meeting

Friday, April 5, 2019, 8:30 – 13:00

Donauhallen, Donaueschingen, Germany

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Agenda

8:00	Welcome coffee, tea, softdrinks
8:30	Opening Remarks Gerfried Zwicker zwickerconsult, Itzehoe, Germany
	CMP Processes: Session 1 Session Chair: Peter Thieme, Infineon Technologies Dresden GmbH, Germany
8:45	L: Advanced CMP for TSV/TGV Wafer Planarization and Introduction to CMP UG-TAIWAN Arthur Chen National Taiwan University for Science and Technology NTUST, Taipei, Taiwan
9:10	L: A Novel Approach to Rational Design of CMP Slurry Kazumi Sugai Fujimi Inc., Kakamigahara, Gifu, Japan
9:35	L: Defining Incoming Raw Slurry and Achieving a Uniform Slurry Mix in the SDS by Using Inline Refractive Index Monitors Marcus Kavaljer K-Patents OY, Vantaa, Finland
10:00	L: Advanced Colloidal Ceria Slurry Challenges Jungyun Kim KCTech Co., Ltd., Anseong-si, Gyeonggi-do, Korea
10:25	**Coffee Break**
	CMP Processes: Session 2 Session Chair: Benjamin Steible, Fraunhofer ISIT, Itzehoe, Germany
11:00	S: Epi ready polishing for SiC Wafer Manuel Kruse Disco Hi-Tech Europe GmbH, Kirchheim, Germany
11:15	L: CMP Outside of the Shrink Race Lotta Römhildt, Frank Reinhold, and Peter Thieme Infineon Technologies Dresden GmbH & Co. KG, Dresden, Germany

11:40 L: Ion Beam Trimming of Wafers - Reaching Out for Further Yield Increase and More Uniform Layers After CMP
Thoralf Dunger, C. Schulze, M. Nestler, and M. Zeuner
SCIA Systems GmbH, Chemnitz, Germany

12:05 L: Process Control Improvement through Multi Endpoint System for STI Process
Gael Royere[3], Kevin Vandersmissen[1], Davy Pittevils[1], Sugawara Masato[2], Ban Ito[2], Takeshi Iizumi[2], Fabien Durix[3], Katia Devriendt[1], Patrick Ong[1] and Herbert Struyf[1]
[1] imec, Leuven, Belgium; [2] Ebara Corporation, Precision Machinery Company, Fujisawa-shi, Japan; [3] Ebara Precision Machinery Europe GmbH, Hanau, Germany

12:30 L: Tbd
Sangback Lee and Seunghyun Jeon
Saesol Diamond Industrial Co., Ltd., Danwon-gu, Ansan-si, Gyeonggi-do, Korea

12:55 Final remarks

13:05 Sandwiches, snacks, tea, coffee, time for discussion

14:00 End of CMP Users Meeting